

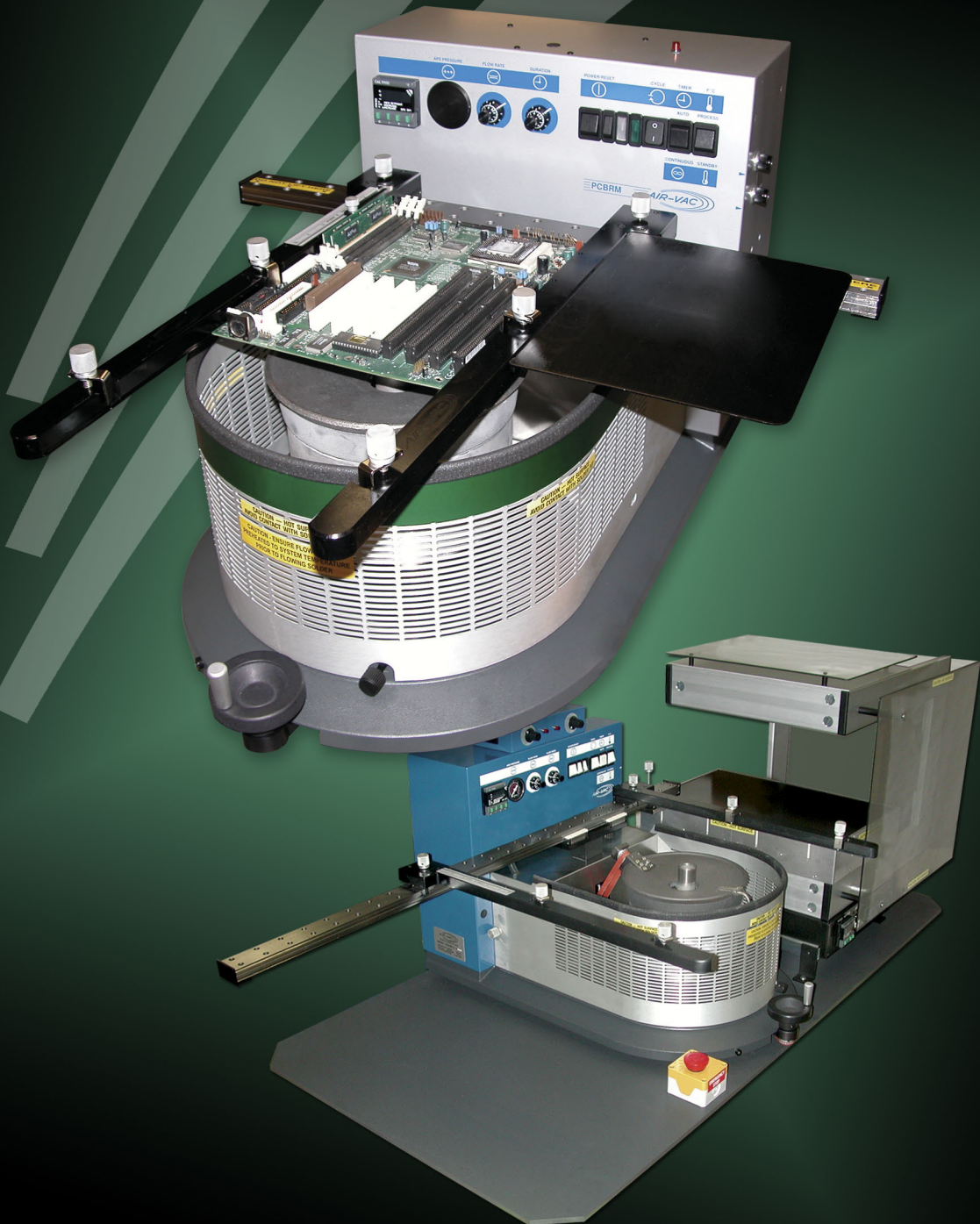
# PCBRM15

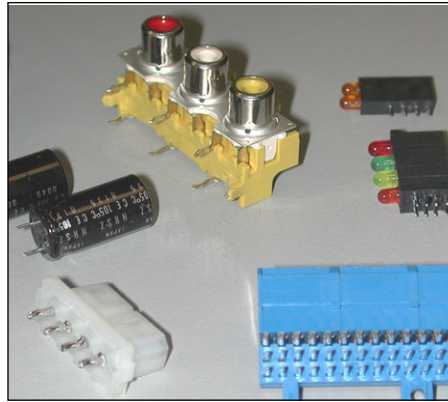
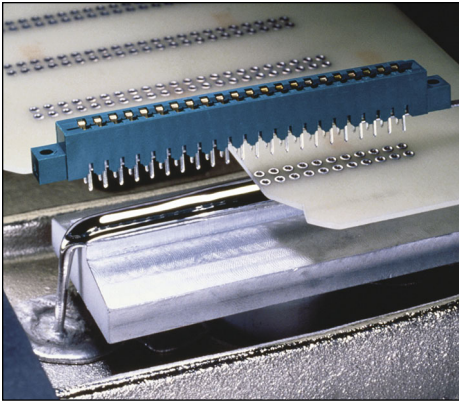


LEAD-FREE SELECTIVE SOLDERING & REWORK OF THROUGH HOLE COMPONENTS. PRECISION CONTROL FOR CHALLENGING BOARD ASSEMBLIES. PCBRM SYSTEM 5.2 ADDS A PREHEATER.

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THROUGH-HOLE SELECTIVE SOLDERING & REWORK





## OVERVIEW

Components are accurately located over a wave of solder whose shape matches the lead pattern. Solder flows for seconds against the bottom of the board, transmitting heat to the leads. When joints are molten, the component is removed. Holes are cleaned with low pressure air and the new component is inserted and resoldered.

## ADVANTAGES

- Lead-Free & thermally challenging assemblies.
- Minimal Copper dissolution in PCB barrels.
- Minimal board delamination.
- Fast and uniform heating.
- Precise operating controls and alignment system.
- Quick component removal and soldering.
- Product reliability.
- Simple design - trouble-free operation.

## FEATURES/BENEFITS

### Pumping System & Solder Pot

- Cast iron solder pot and titanium/cast iron impeller pump are designed to withstand aggressive, lead-free solder.
- Minimal dross accumulation and level solder wave.

### Precise Operating Control

- Solder Wave Contact - Cycle duration automatically sets time solder contacts board.
- Solder Wave Flow Rate - allows level wave for any flow well shape or size. Three (3) stage settings for enhanced process control.
- Temperature - Microprocessor provides closed-loop control of set temperature. System can be set to 615°F (325°C).

### Alignment System

- X, Y, Z Board Carrier - Cantilever rails, linear bearings and rigid cast framework provides large board holding, precision rail movement and continuous usage.
- PCB Hole Cleaning System (option) - Component is aligned over solder wave then cleaning hood is positioned to clean PCB barrels.

## APPLICATION SPECIFIC TOOLING

### Titanium Flow Wells

- Solder flow is directed away from adjacent components.
- High pin count leads are heated simultaneously for a quick process.
- Locating pins position the lead pattern over the solder wave.
- External heaters maintain uniform heat on large flow wells.
- Fixtures for multiple and irregularly shaped boards.

## OPTIONS

- APS - PCB Hole Cleaning System
- ST350 Flow Well Heater Control Module
- Fume Extraction Module

## TECHNICAL DATA

### PCBRM15

- *Physical Dimensions:* 32"W x 32"D x 26"H
- *Solder Capacity:* 35 lbs. Weight with Solder: 125 lbs.
- *Compressed Air:* 40-80 psi, clean moisture free
- *Electrical:* 208/220V, 15 amps @ 220V, 50/60Hz single phase, 2500 watts.

### PCBRM System 5.2

- *Physical Dimensions:* 76"W x 33"D x 28"H
- *Board Carrier Size:* 24"W x 20"D
- *Solder Capacity:* 35 lbs. Weight with Solder: 230 lbs.
- *Compressed Air:* 40-80 psi, clean moisture free
- *Electrical:* 45 amps @ 220V, 50/60Hz, 10000 watts.

**TECHNICAL DATA SUBJECT TO CHANGE.**



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